ZMD31010 RBic$_{Lite}$™ Technical Notes
Die Dimensions and Pad Coordinates

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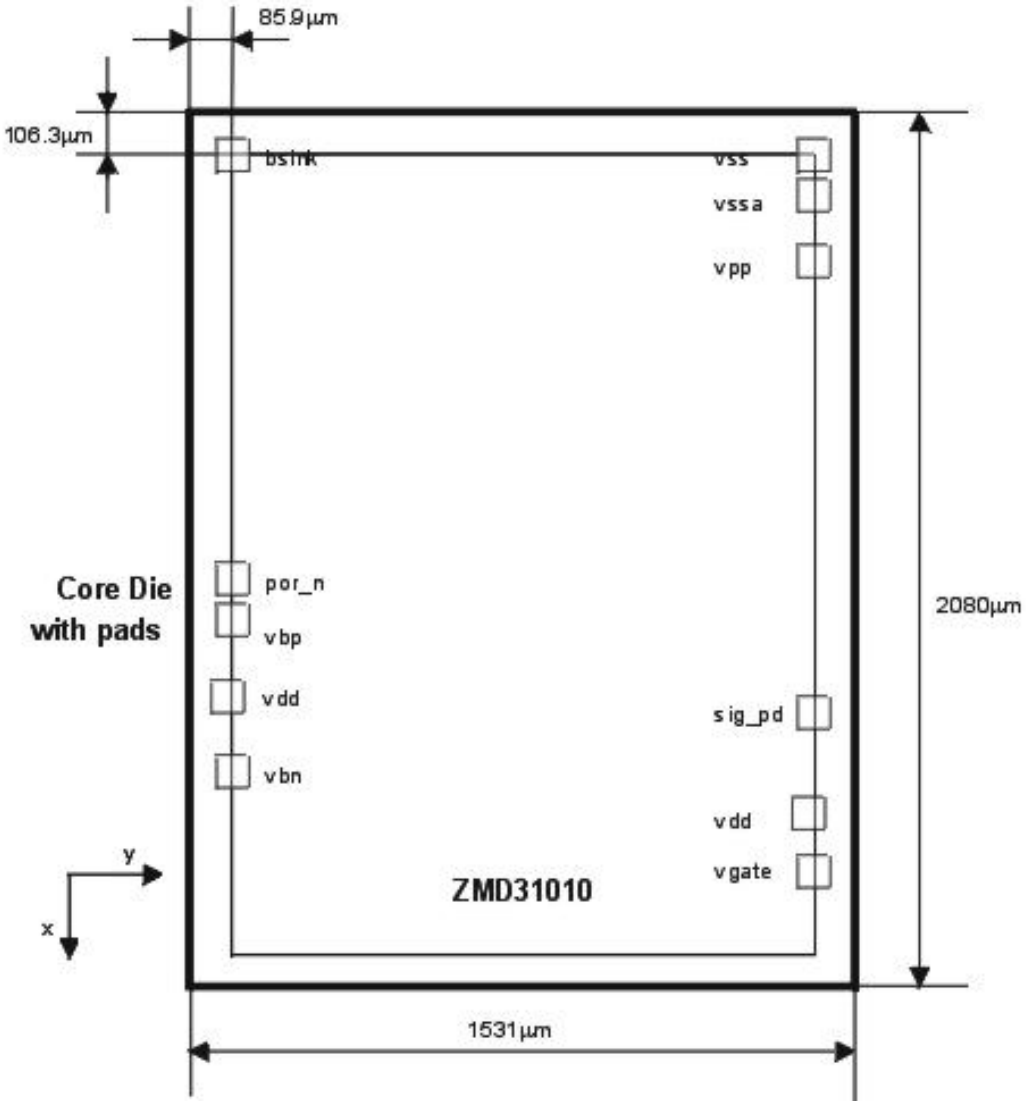
1 RBic$_{Lite}$™ Die Dimensions

- Die size (including scribeline): 2230 µm x 1681 µm ≈ 3.75sqmm
- Core die size (without scribeline): 2080 µm x 1531 µm ≈ 3.19 sqmm
- Die thickness: 390µm
- Scribeline (distance between two core dice on wafer): 150µm
- Pads size: 68µm x 68µm



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2 RBic$_{Lite}$™ Pad Coordinates

All pads coordinates are for pad centers and related to the corner.

Name	X Coordinate in µ	Y Coordinate in µ
bsink	106.3	85.9
por_n	1109.7	85.9
vbp	1210.0	85.9
vdd	1389.3	77.3
vbn	1568.1	85.9
vss	107.2	1444.7
vssa	198.3	1444.7
vpp	356.1	1444.7
sig_pd	1428.6	1444.7
vdd	1672.3	1435.8
vgate	1809.2	1444.7

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3 Related Documents

- ZMD31010 RBic$_{Lite}$™ Datasheet
- ZMD31010 RBic$_{Lite}$™ Development Kit Documentation
- ZMD31010 RBic$_{Lite}$™ Errata Sheet
- ZMD31010 RBic$_{Lite}$™ Application Notes – In-Circuit Programming Boards

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